Company :	**Qualcomm India Pvt Ltd**
Company Name :	**Qualcomm India Pvt Ltd**
Nature Of Business :	**Semi Conductor**
Designation :	**Interim Intern Engineer**
Tentative Job Location :	Hyderabad/Bangalore/Noida/Chennai

Interim Intern Engineer- Hardware

Job Area :Engineering Job Location :   Bangalore / Hyderabad /Chennai / Noida

Description :

We know our employees' ideas change the world. For more than three decades, we've been a global leader in mobile technology, continually pushing the boundaries of what's possible. Working with customers across industries — from automotive to health care, from smart cities to robotics— we continue to accelerate innovation and unlock new possibilities in a time where everything is connected. By joining the Qualcomm family, you too can bring the future forward faster.   Qualcomm is looking for an energetic, creative and self-driven engineer to work in Modem , Multimedia , Connectivity , Computer Vision and Image Processing , software implementation and hardware acceleration. The work will directly influence the various subsystems within the SoC. The ideal candidate would have very strong problem solving and analytical skills combined with creativity and a passion for innovation. They would be able to carry forward that new idea, concept, and/or application that will propel systems to new levels of effectiveness and efficiency. At Qualcomm you will perform detailed technical analysis, translate ideas into models, SW and/or HW and work closely with other teams to help deliver real products. At Qualcomm, the sky's the limit. College Graduates play important roles everywhere in the company. Many of our 27,000+ employees join us right out of school because we're working on the cutting edge in wireless. Complex wireless devices are only as powerful as the software that runs them. As a software engineer, you will develop, implement and maintain multimedia, gaming and application software for the world's leading-edge mobile devices. We know our employees' ideas change the world. For more than three decades, we've been a global leader in mobile technology, continually pushing the boundaries of what's possible. Working with customers across industries — from automotive to health care, from smart cities to robotics— we continue to accelerate innovation and unlock new possibilities in a time where everything is connected. By joining the Qualcomm family, you too can bring the future forward faster.

• SOC & Hard Macro Physical Design • SOC Validation & Debug • RF & Analog Layout • RF/Analog/Mixed Signal/Power IC Design • Low Power Design • Board and FPGA Design\ • Digital ASIC Design • Design/SOC Verification • CAD Solution Engineer • Design for Test (DFT) • CPU Desig Must have educational background in one or more of the following areas:

• Verifying SoC with embedded RISC/DSP processors, communications/ networking ASICs. • Verilog or VHDL, C/C++, Tcl/Perl/shell-scripting. RTL design experience and/or strong OO programming knowledge • Knowledge of wireless/wired communications and protocols or graphics/video multimedia is a plus. • Knowledge in PLL, LNA, OpAmp, CMOS, ADC/DAC, Cadence, SpectreRF, or Layout is required in RF/Analog/Mixed Signal IC Design. • Excellent analytical and problem solving skills. • Ability to collaborate and work in teams. • Good verbal and written communication skill

Educational Background:

Masters, Bachelors: Electrical Engineering , VLSI , Embedded and VLSI , ECE

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Interim Intern Engineer- Software

Job Area :Engineering - Software
Job Location : Hyderabad / Bangalore / Chennai / Noida
We know our employees' ideas change the world. For more than three decades, we've been a global leader in mobile technology, continually pushing the boundaries of what's possible. Working with customers across industries — from automotive to health care, from smart cities to robotics— we continue to accelerate innovation and unlock new possibilities in a time where everything is connected. By joining the Qualcomm family, you too can bring the future forward faster.   As a software engineer, you will design, develop Software for Qualcomm's mobile chipsets which are based on cutting edge technology. Qualcomm is looking for energetic,

creative and self-driven engineer to work in

• Multimedia Technologies such as Audio and Video codecs, • Wireless Modem Technologies, such as 4G, WiFi, Bluetooth, Self-Organizing Networks. • Platform Level SW, such as, Linux, Android, Windows, Board Support Packages. • IOT Technologies, for Connected Cameras, Smart Assistants, Drones, Virtual Reality, Augmented Reality.

Campus Grads will be working on following areas:
• Development of real-time embedded software and device drivers • Mobile SW development for Windows Mobile, Android or Linux • Good understanding of OS concepts, Data structures, etc • C/C++ and object oriented design • Wireless network standards such as CDMA/GSM/UMTS/LTE • Linux/UNIX, Linux Drivers, Linux Kernel Development • Protocols such TCP/UDP/IP/SIP/RTP etc • Multimedia technologies including Audio, Video, Imaging • Excellent analytical and problem solving skills • Ability to collaborate and work in teams. • Good verbal and written communication skill

Opportunities include:
• SW development for Android, Window Mobile based Embedded Platforms • Multimedia software stack, firmware and driver Development • Wireless Modem and connectivity Software and Firmware Development • Communication protocol stack Software Development • Kernel, BSP and Device Driver Development • Application SW and UI development. • SW Architecture for embedded devices based on Android, Windows. • Design and development based on Object oriented programming.

Education:
Masters, Bachelors: Computer Science Engineering, Communication Engineering, ECE,

Interim Intern Engineer-Software

Eligibilty :

Program	AE	BSBE	CE	CHE	CSE	EE	ES	ME	MSE	PHY	CHM	MTH	ECO	DES	IME	HSS
BT-BS	No	No	No	No	Yes	Yes	No	No	No	No	No	No	No	--	--	--
MT	No	No	No	No	No	No	No	No	No	--	--	--	--	--	No	--
DoubleMajor	No	No	No	No	Yes	Yes	No	No	No	No	No	No	No	--	--	--
dual	No	No	No	No	Yes	Yes	No	No	No	No	No	No	No	--	--	--
dualB	No	No	No	No	--	--	--	No	No	No	No	No	No	--	No	--
dualC	--	--	--	--	--	--	--	--	--	--	--	--	--	--	No	--
Mdes	--	--	--	--	--	--	--	--	--	--	--	--	--	No	--	--
MBA	--	--	--	--	--	--	--	--	--	--	--	--	--	--	No	--
Phd	No	No	No	No	No	No	No	No	No	No	No	No	No	--	--	No
Msc	--	--	--	--	--	--	--	--	--	No	No	No	No	--	--	--
MSR	--	--	--	--	--	--	--	--	--	--	--	--	--	--	--	--

Stipend per month :	**45000 per month**
Other Facilities Offered :	**Accomodation for entire internship period**
	To and Fro Flight
Bond :	**False**
CPI CutOff :	**0.0**
Medical Requirments :	**No**
Resume Shortlist :	**False**
Aptitude Test:	**False**
Group Discussion:	**False**
Technical Test:	**True**
Technical Test Duration:	**90 mins**
Technical Interview:	**True**
Technical	

Interview Duration:	**45 mins**
Number of Techincal Interview Rounds:	**1**
HR Interview:	**True**
HR Interview Duration:	**30 mins**
Additional Information:	